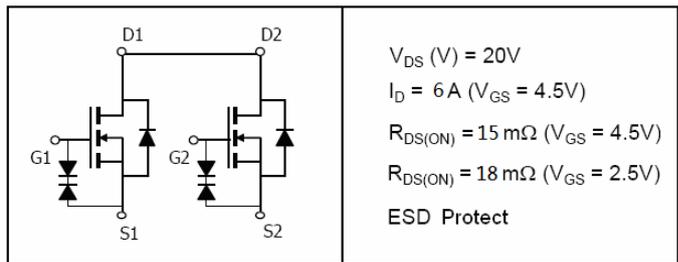


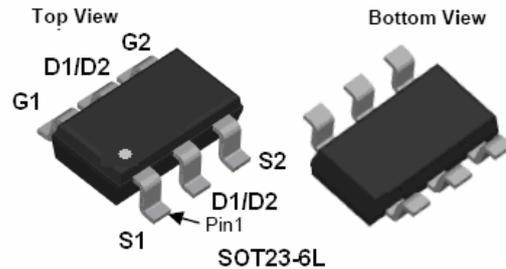
### Features

- ◆ Ron(typ.)=15mΩ @VGS=4.5V
- ◆ Low On-Resistance
- ◆ Fast Switching
- ◆ ESD Protection
- ◆ Green Product



### Description

VS6808AH designed by the trench processing techniques to achieve extremely low on-resistance, fast switching speed and improved transfer effective. These features combine to make this design an extremely efficient and reliable device for variety of DC-DC applications.



### Absolute Maximum Ratings

Symbol	Parameter		Rating	Unit
<b>Common Ratings (T<sub>c</sub>=25°C Unless Otherwise Noted)</b>				
V <sub>GS</sub>	Gate-Source Voltage		±10	V
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage		20	V
T <sub>J</sub>	Maximum Junction Temperature		150	°C
T <sub>STG</sub>	Storage Temperature Range		-50 to 155	°C
I <sub>S</sub>	Diode Continuous Forward Current	T <sub>c</sub> = 25°C	6 <sup>①</sup>	A
ESD	HBM		2000	V
<b>Mounted on Large Heat Sink</b>				
I <sub>DM</sub>	Pulse Drain Current Tested	T <sub>c</sub> = 25°C	24 <sup>①</sup>	A
I <sub>D</sub>	Continuous Drain Current(VGS=4.5V)	T <sub>c</sub> = 25°C	6 <sup>①</sup>	A
		T <sub>c</sub> = 70°C	4.5	
P <sub>D</sub>	Maximum Power Dissipation	T <sub>c</sub> = 25°C	1.15	W
		T <sub>c</sub> = 70°C	0.8	
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient		120	°C/W

**Typical Electrical Characteristics**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	20	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (T <sub>c</sub> =25°C)	V <sub>DS</sub> =16V, V <sub>GS</sub> =0V	--	--	1	μA
	Zero Gate Voltage Drain Current(T <sub>c</sub> =100°C)	V <sub>DS</sub> =16V, V <sub>GS</sub> =0V	--	--	100	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±4.5V, V <sub>DS</sub> =0V	--	--	±1	μA
		V <sub>GS</sub> =±8V, V <sub>DS</sub> =0V	--	--	±10	μA
V <sub>GS(TH)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	0.5	0.7	1.0	V
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =4.5V, I <sub>D</sub> =6A	--	15	20	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =5A	--	18	25	mΩ
		V <sub>GS</sub> =1.8V, I <sub>D</sub> =2A	--	22	35	mΩ
<b>Dynamic Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =5V, V <sub>GS</sub> =0V, f=1MHz	--	710	--	pF
C <sub>oss</sub>	Output Capacitance		--	180	--	pF
C <sub>riss</sub>	Reverse Transfer Capacitance		--	85	--	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =10V, I <sub>D</sub> =1A, V <sub>GS</sub> =4.5V	--	9	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	1.8	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	4	--	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =10V, I <sub>D</sub> =1A, R <sub>G</sub> =3Ω, V <sub>GS</sub> =4.5V, R <sub>L</sub> =5Ω,	--	200	--	ns
t <sub>r</sub>	Turn-on Rise Time		--	400	--	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		--	12	--	ns
t <sub>f</sub>	Turn-Off Fall Time		--	6	--	ns
<b>Source- Drain Diode Characteristics</b>						
V <sub>SD</sub>	Forward on voltage	T <sub>J</sub> =25°C, I <sub>SD</sub> =3A, V <sub>GS</sub> =0V	--	0.7	1.3	V
Q <sub>rr</sub>	Reverse Recovery Charge	I <sub>SD</sub> =6A, di/dt=100A/μs	--	10	--	nC
t <sub>rr</sub>	Reverse Recovery Time		--	26	--	ns

Notes: ① Pulse test ; Pulse width≤300μs, duty cycle≤2%.

## Typical Characteristics

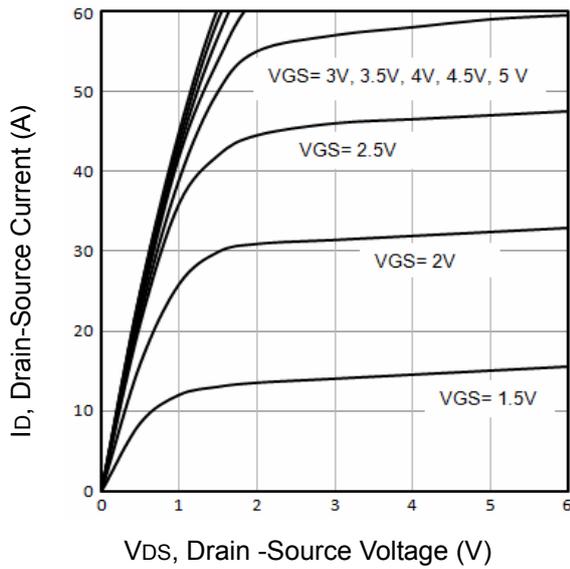


Fig1. Typical Output Characteristics

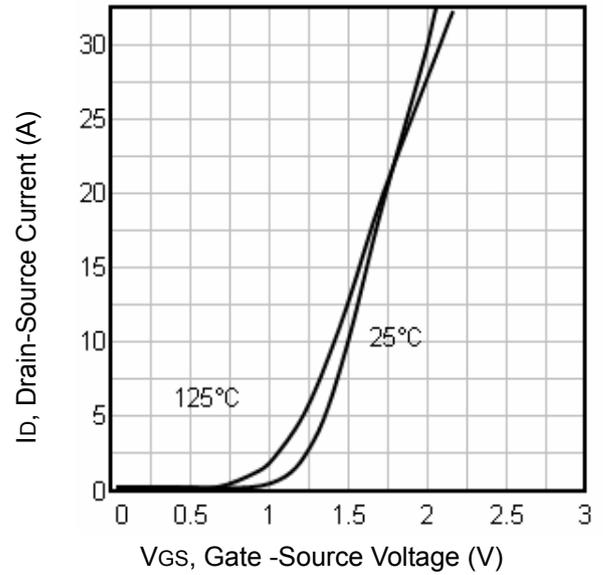


Fig2. Typical Transfer Characteristics

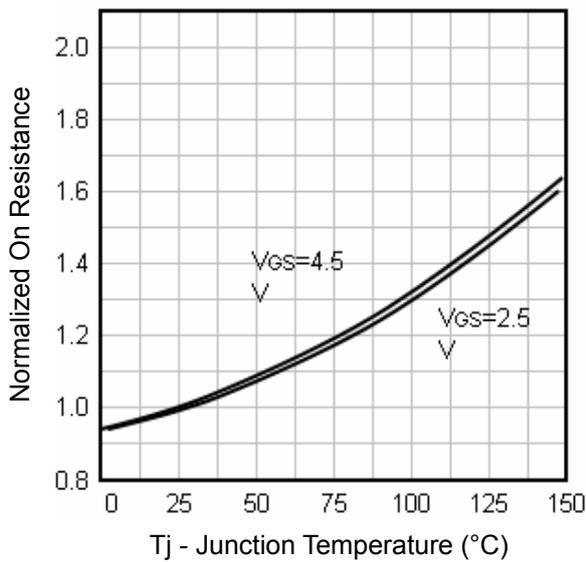


Fig3. Normalized On-Resistance Vs. Temperature

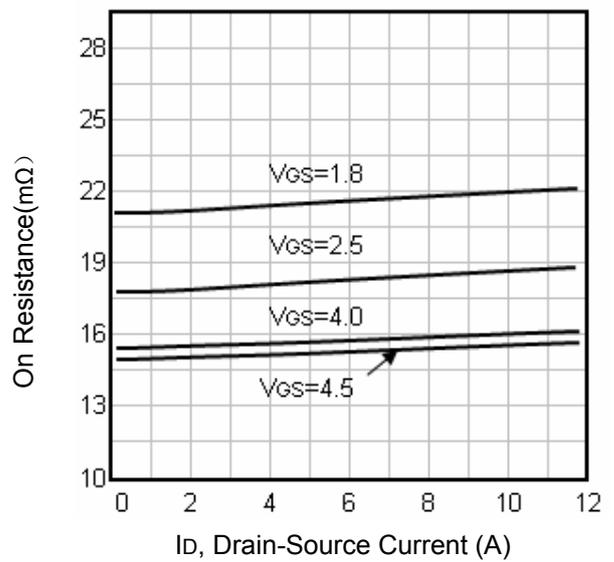


Fig4. On-Resistance Vs. Drain-Source Current

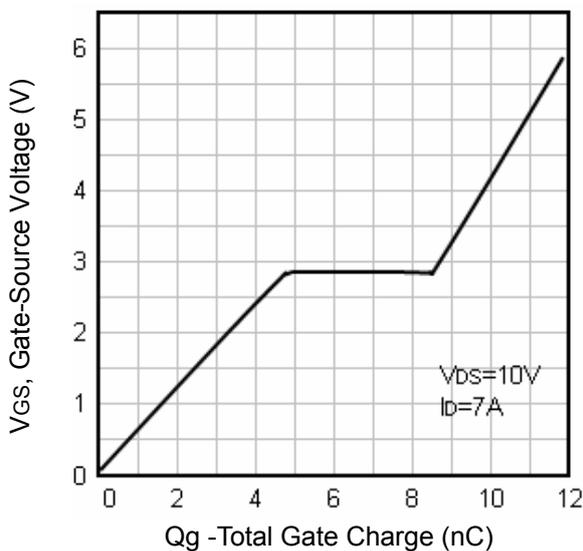


Fig5. Typical Gate Charge Vs. Gate-Source Voltage

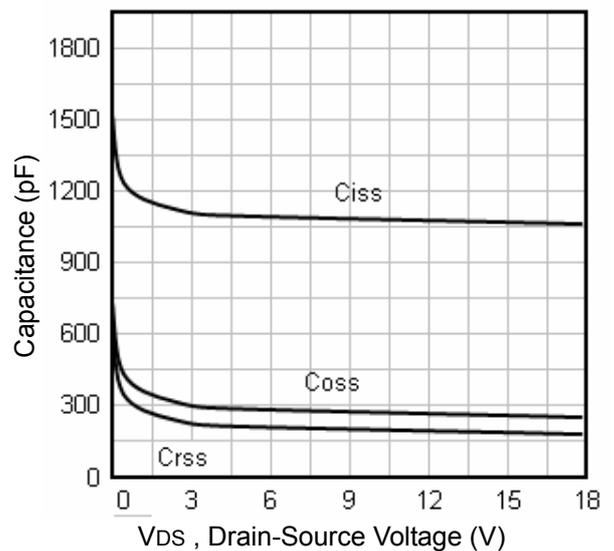


Fig6 Typical Capacitance Vs. Drain-Source Voltage

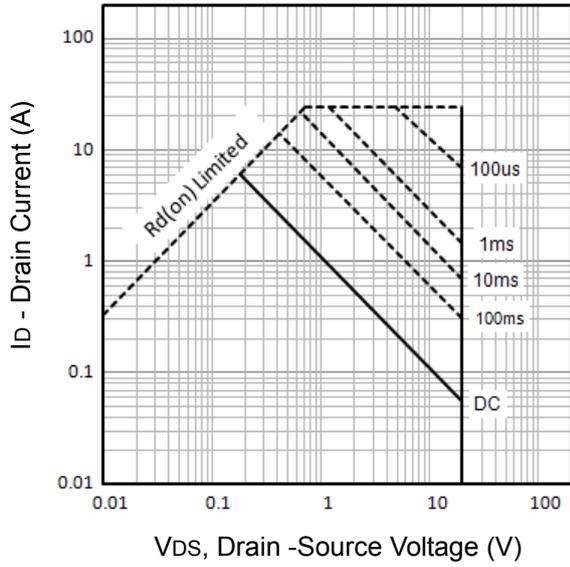


Fig7. Maximum Safe Operating Area

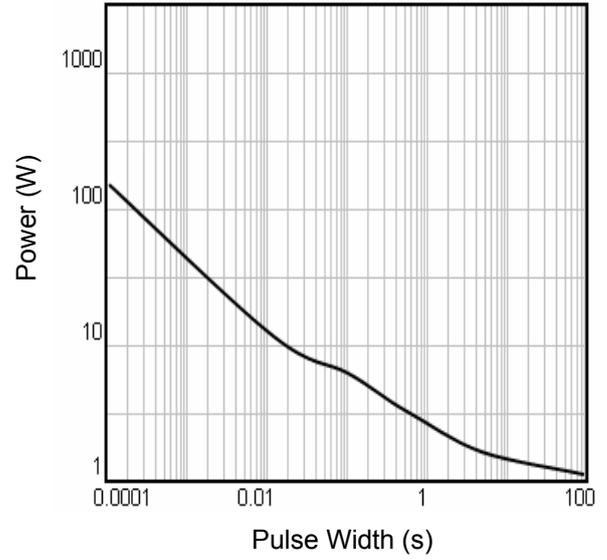


Fig8. Typical Single Puls Power Rating Junction-to-Ambient

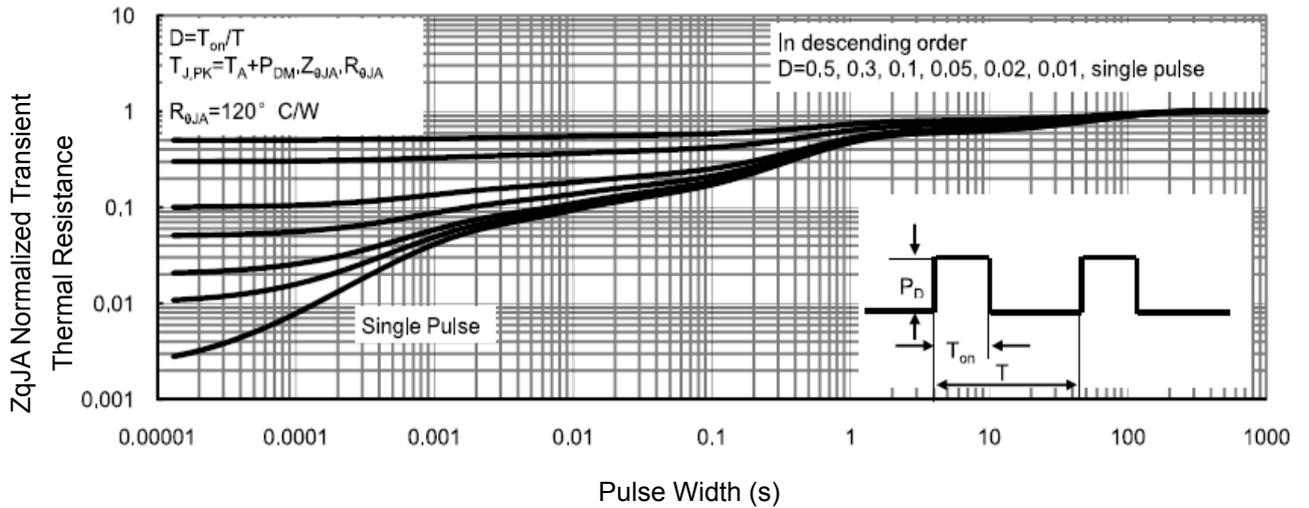


Fig9. Normalized Maximum Transient Thermal Impedance

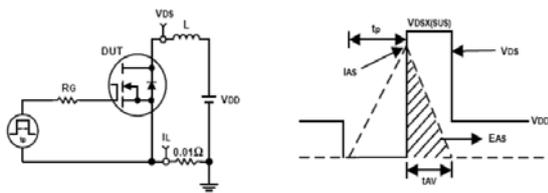


Fig10. Unclamped Inductive Test Circuit and waveforms

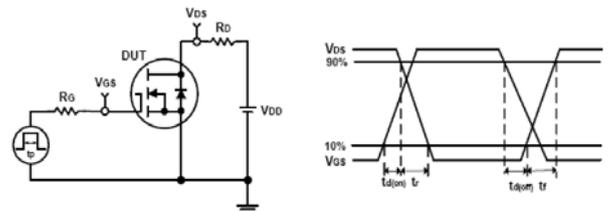
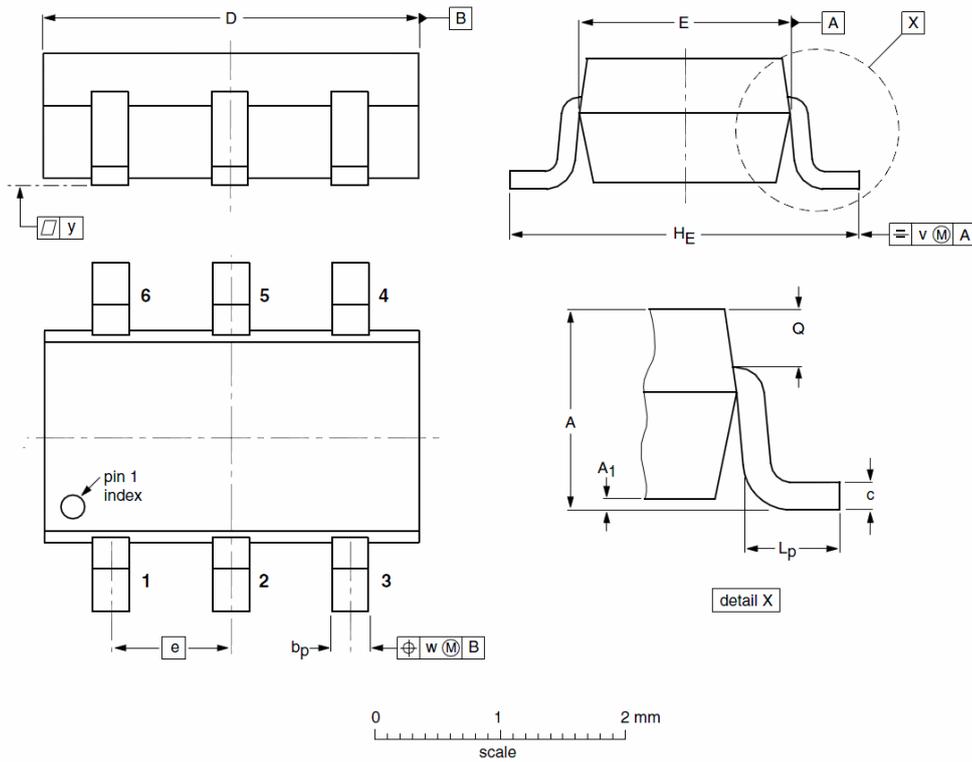


Fig11. Switching Time Test Circuit and waveforms

**SOT23-6L Package Outline Data**



**DIMENSIONS ( unit : mm )**

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.07	1.10	A <sub>1</sub>	0.01	0.05	0.10
b <sub>p</sub>	0.25	0.35	0.40	c	0.10	0.18	0.26
D	2.70	2.92	3.10	E	1.30	1.55	1.70
e	--	0.95	--	H <sub>E</sub>	2.50	2.80	3.00
L <sub>p</sub>	0.20	0.38	0.60	Q	0.23	0.29	0.33
v	--	0.20	--	w	--	0.20	--
y	--	0.10					

**Order Information**

Product	Marking	Package	Packaging	Min Unit Quantity
VS6808A	V688	SOT23-6	3000/Reel	6000

**Customer Service**

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